



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE4473G V55-2			<b>Issued</b>	25. January 2018			
<b>MA#</b>	MA000668512							
<b>Package</b>	PG-DSO-12-11			<b>Weight*</b>	404.76 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.438	1.84	1.84	18376	18376
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		171	
	non noble metal	iron	7439-89-6	0.230	0.06		569	
wire	non noble metal	copper	7440-50-8	230.106	56.82	56.90	568505	569245
	non noble metal	aluminium	7429-90-5	0.143	0.04	0.04	353	353
encapsulation	organic material	carbon black	1333-86-4	0.308	0.08		762	
	plastics	epoxy resin	-	14.188	3.51		35053	
leadfinish	inorganic material	silicondioxide	60676-86-0	139.720	34.52	38.11	345195	381010
	non noble metal	tin	7440-31-5	4.235	1.05	1.05	10464	10464
plating	inorganic material	phosphorus	7723-14-0	0.002	0.00		4	
	non noble metal	nickel	7440-02-0	0.630	0.16	0.16	1556	1560
solder	non noble metal	tin	7440-31-5	0.154	0.04		380	
	noble metal	silver	7440-22-4	0.192	0.05		475	
*deviation	non noble metal	lead	7439-92-1	7.341	1.81	1.90	18137	18992
				Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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